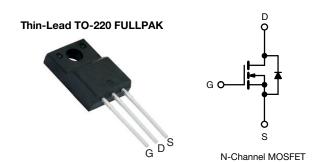
Vishay Siliconix

E Series Power MOSFET



PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	550)
R _{DS(on)} max. (Ω) at 25 °C	V _{GS} = 10 V	0.243
Q _g max. (nC)	66	
Q _{gs} (nC)	8	
Q _{gd} (nC)	14	
Configuration	Sing	le

FEATURES

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>



APPLICATIONS

- Computing
 - PC silver box / ATX power supplies
- Lighting
 - Two stage LED lighting
- Consumer electronics
- Applications using hard switched topologies
 - Power factor correction (PFC)
 - Two switch forward converter
 - Flyback converter
- Switch mode power supplies (SMPS)

ORDERING INFORMATION				
Package	Thin-Lead TO-220 FULLPAK			
Lead (Pb)-free	SiHA15N50E-E3			
Lead (Pb)-free and halogen-free	SiHA15N50E-GE3			

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, un	less otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	500	V
Gate-source voltage			V_{GS}	± 30	
Continuous drain augrent /T 150 °C) 6	\/ -+ 10\/	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$		14.5	
Continuous drain current (T _J = 150 °C) ^e	V _{GS} at 10 V	T _C = 100 °C	I _D	9.2	А
Pulsed drain current ^a			I _{DM}	28	
Linear derating factor				1.25	W/°C
Single pulse avalanche energy b			E _{AS}	136	mJ
Maximum power dissipation			P_{D}	33	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope	V _{DS} = 0 V to 80 % V _{DS}		dV/dt	70	V/ns
Reverse diode dV/dt ^d			αν/αι	27	V/IIS
Soldering recommendations (peak temperature) c	for	10 s		300	°C
Mounting torque M3 screw				0.6	Nm

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3.1 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$
- e. Limited by maximum junction temperature



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	3.8	G/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		_			l .	•	<u> </u>
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		500	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	=.	0.62	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I_{GSS}		V _{GS} = ± 30 V	-	-	± 1	μΑ
Zoro goto voltogo drain ourrent		V _{DS} =	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$		=.	10	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 400 \	/, V _{GS} = 0 V, T _J = 125 °C	=.	=.	25	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 7.5 A	-	0.243	0.280	Ω
Forward transconductance	9 _{fs}	$V_{DS} = 30 \text{ V}, I_{D} = 7.5 \text{ A}$		-	3.9	-	S
Dynamic		•				•	
Input capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		=	1162	-	pF
Output capacitance	C _{oss}			-	51	-	
Reverse transfer capacitance	C _{rss}			-	7	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	55	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	164	-	
Total gate charge	Qg			-	33	66	
Gate-source charge	Q_{gs}	V _{GS} = 10 V	$I_D = 7.5 \text{ A}, V_{DS} = 400 \text{ V}$	-	8	-	nC
Gate-drain charge	Q _{gd}	7		-	14	-	
Turn-on delay time	t _{d(on)}			-	15	30	
Rise time	t _r	V_{DD} = 400 V, I_{D} = 12 A, V_{GS} = 10 V, R_{a} = 9.1 Ω		-	24	48	ns
Turn-off delay time	t _{d(off)}			-	34	68	
Fall time	t _f		-		18	36	
Gate input resistance	R_g	f = 1 MHz, open drain		-	0.85	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	Is	MOSFET sym showing the	MOSFET symbol showing the		-	14.5	
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	28	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 7.5 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	T _J = 25 °C, $I_F = I_S = 7.5 \text{ A}$, dl/dt = 100 A/ μ s, $V_R = 25 \text{ V}$		-	265	-	ns
Reverse recovery charge	Q _{rr}			-	3.2	-	μC
Reverse recovery current	I _{RRM}			_	23	_	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

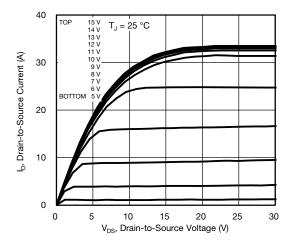


Fig. 1 - Typical Output Characteristics

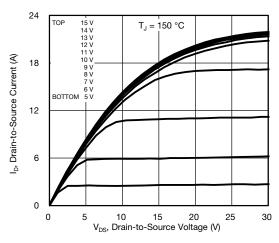


Fig. 2 - Typical Output Characteristics

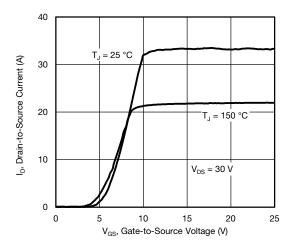


Fig. 3 - Typical Transfer Characteristics

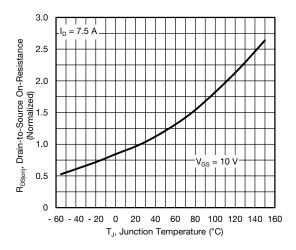


Fig. 4 - Normalized On-Resistance vs. Temperature

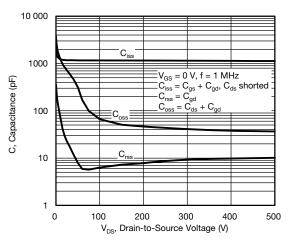


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

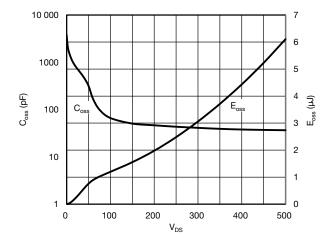


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



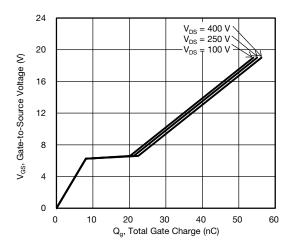


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

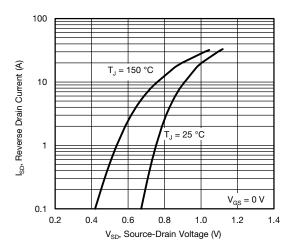


Fig. 8 - Typical Source-Drain Diode Forward Voltage

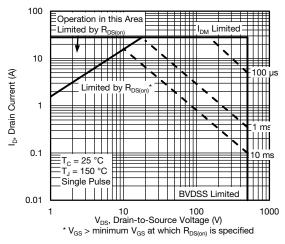


Fig. 9 - Maximum Safe Operating Area

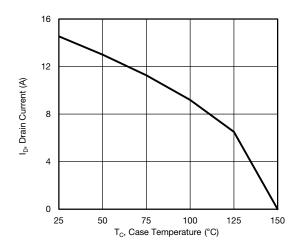


Fig. 10 - Maximum Drain Current vs. Case Temperature

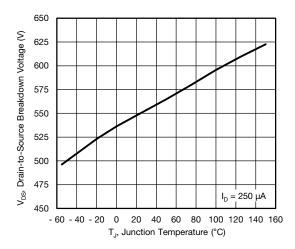


Fig. 11 - Temperature vs. Drain-to-Source Voltage



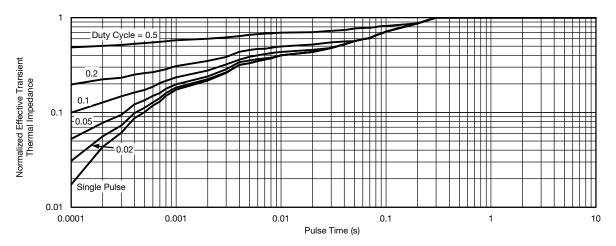


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

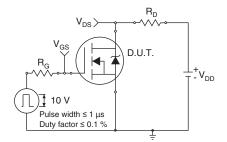


Fig. 13 - Switching Time Test Circuit

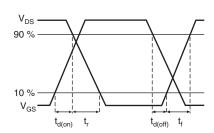


Fig. 14 - Switching Time Waveforms

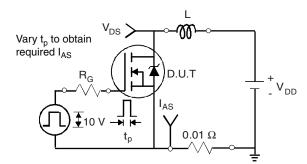


Fig. 15 - Unclamped Inductive Test Circuit

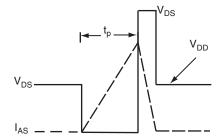


Fig. 16 - Unclamped Inductive Waveforms

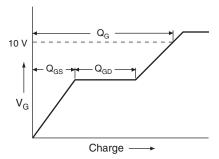


Fig. 17 - Basic Gate Charge Waveform

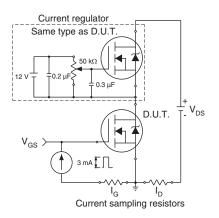
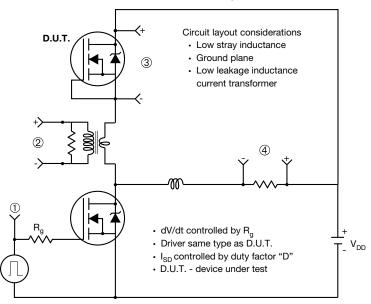


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



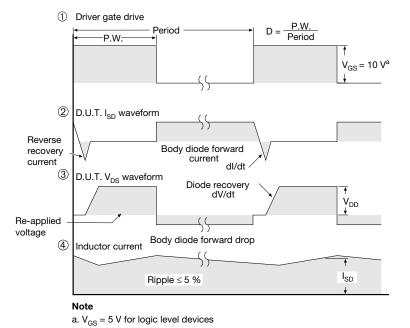


Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead





SYMBOL		DIMEN	ISIONS	
	MILLIN	IETERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
Α	4.30	4.70	0.169	0.185
A1	2.50	2.90	0.098	0.114
A2	2.40	2.80	0.094	0.110
b	0.60	0.80	0.024	0.031
b2	0.60	0.90	0.024	0.035
С	=	0.60	-	0.024
D	8.30	8.70	0.327	0.342
d1	14.70	15.30	0.579	0.602
d2	2.90	3.10	0.114	0.122
d3	3.30	3.70	0.130	0.146
Е	9.70	10.30	0.382	0.406
е	2.50	2.70	0.098	0.106
L	13.40	13.80	0.528	0.543
L1	1.00	2.80	0.039	0.110
ØP	3.00	3.40	0.118	0.134

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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Vishay

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